# Voltage Regulator - SCSI-2 **Active Terminator, Low Dropout**

### 800 mA, 2.85 V

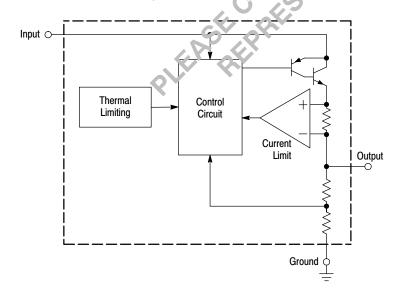
The MC34268 is a medium current, low dropout positive voltage regulator specifically designed for use in SCSI-2 active termination circuits. This device offers the circuit designer an economical solution for precision voltage regulation, while keeping power losses to a minimum. The regulator consists of a 1.0 V dropout composite PNP/NPN pass transistor, current limiting, and thermal limiting These devices are packaged in the SOIC-8 and DPAK-3 SOT-223 surface mount power packages.

Applications include active SCSI-2 terminators 2 regulation of switching power supplies.

#### **Features**

- 2.85 V Output Voltage for SCSI-2 Active Termina.
- 1.0 V Dropout
- Output Current in Excess of 800 mA
- Thermal Protection
- Short Circuit Protection
- Output Trimmed to 1.4% Tolera
- No Minimum Load Re are
- and SOIC-8 Surfice Mourt • Space Saving DPAK-Power Packages
- Pb-Free Pac' ges an van 1e

### Simplified Block Diagram



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SOIC-8 **D SUFFIX CASE 751** 

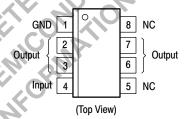


= Assembly Location

= Wafer Lot

= Year

W = Work Week





DPAK-3 **DT SUFFIX** CASE 369A





SOT-223 ST SUFFIX **CASE 318E** 





Pin 1. Ground 2. Output

3. Input

4. Output

Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Power Supply Input Voltage	V <sub>in</sub>	15	V
Power Dissipation and Thermal Characteristics			
DT Suffix, Plastic Package, Case 369A			
$T_A = 25$ °C, Derate Above $T_A = 25$ °C	$P_{D}$	Internally Limited	W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	5.0	°C/W
Thermal Resistance, Junction-to-Air	$R_{ heta JA}$	87	°C/W
D Suffix, Plastic Package, Case 751			
$T_A = 25$ °C, Derate Above $T_A = 25$ °C	$P_{D}$	Internally Limited	W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	22	°C/W
Thermal Resistance, Junction-to-Air	$R_{ heta JA}$	140	°C/W
ST Suffix, Plastic Package, Case 318E			
$T_A = 25$ °C, Derate Above $T_A = 25$ °C	P <sub>D</sub>	Internally Limited	W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	15	°C/W
Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	245	°C/W
Operating Ambient Temperature Range	I <sub>A</sub>	0 to +125	°C
Maximum Die Junction Temperature	TJ	+150	°C
Storage Temperature	T <sub>stg</sub>	- 5₺ to +150	°C

Maximum ratings are those values beyond which device damage can or ... Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If it is a limit are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{in} = 4.25 \text{ V}, C_{O} = 10 \mu\text{F}, \text{ for typical values } T_{A} = 25^{\circ}\text{C}, \text{ for i.} \text{ 'max value'} T_{A} = 0^{\circ}\text{C to } +12 \text{C} \text{ unless of herwise in ted.})$ 

Characteristic	Symbol	Mir	Тур	Max	Unit
Output Voltage (T <sub>A</sub> = 25°C, I <sub>O</sub> = 0 mA)	) Vo	2 61	2.85	2.89	V
Output Voltage, over Line, Load, and Tempei re (V <sub>in</sub> = ) V to 15 V, I <sub>O</sub> = 0 mA to 490 mA)	500	1.76	2.85	2.93	
Line Regulation ( $V_{in} = 4.25 \text{ V to } 15 \text{ V}$ $_0 = 0$ $_1 = 25 ^{\circ}\text{C}$ )	Reg. Tie	-	-	0.3	%
Load Regulation (I <sub>O</sub> = 0 mA to 200 mA, A = 25°C	r ≏g <sub>load</sub>	-	-	0.5	%
Dropout Voltage (I <sub>O</sub> = 490 ° .)	V <sub>in</sub> – V <sub>O</sub>	1	0.95	1.1	V
Ripple Rejection (f = 120 h.	RR	55	-	-	dB
Maximum Output V <sub>in</sub> = ^ /	I <sub>(max)</sub>	800	-	-	mA
Bias Current (\ = 4.25 V, = 0 mA)	I <sub>B</sub>	1	5.0 to 3.0	8.0	mA
Minimum Load Contain Regulation (V <sub>In</sub> = 15 V)	I <sub>L(min)</sub>	ı	_	0	mA

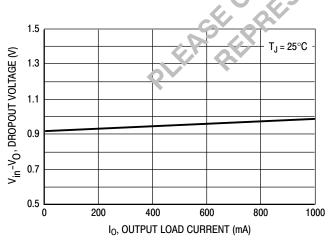


Figure 1. Dropout Voltage versus
Output Load Current

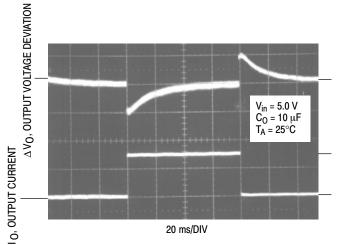


Figure 2. Transient Load Regulation

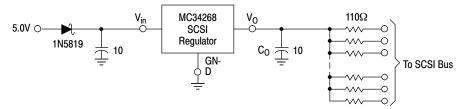


Figure 3. Typical SCSI Application

Figure 3 is a circuit of a typical SCSI terminator application. The MC34268 is designed specifically to provide 2.85 V required to drive a SCSI–2 bus. The output current capability of the regulator is in excess of 800 mA; enough to drive standard SCSI–2, fast SCSI–2, and some wide SCSI–2 applications. The typical dropout voltage is less than 1.0 V, allowing the IC to regulate to input voltages less than 4.0 V. Internal protective features include current and thermal limiting.

The MC34268 requires an external 10  $\mu F$  capacitor with an ESR of less than 10  $\Omega$  for stability over temperature. With economical electrolytic capacitors, cold temperature operation can rose a stability problem. As temperature decreases, the capacitance also decreases and the ESR increases, nich could cause the circuit to oscillate. Tantaly capers represent the capacitance and ESR of a tantalum capacitance is more stable over temperature

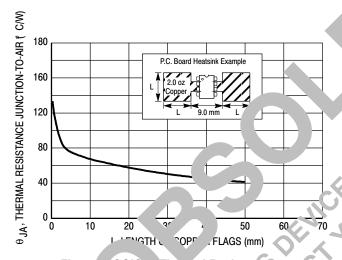


Figure . SOIC- Thermal Resistance versus P.C.I Copper Length

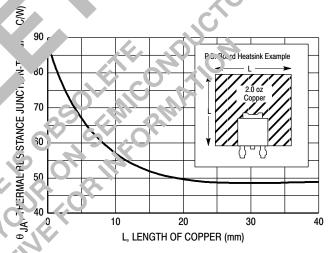


Figure 5. DPAK-3 Thermal Resistance versus P.C.B. Copper Length

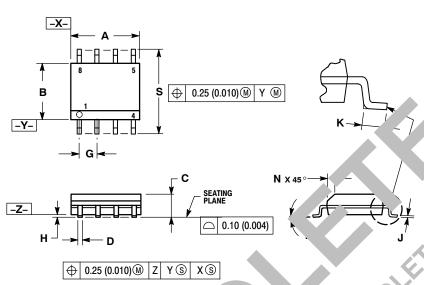
### **ORDERING INFORMATION**

Device	<b>♥ackage</b>	Shipping Information <sup>†</sup>	
MC34268D	SOIC-8	98 Units / Rail	
MC34268DG	SOIC-8 (Pb-Free)	98 Units / Rail	
MC34268DR2	SOIC-8	2500 Units / Tape & Reel	
MC34268DR2G	SOIC-8 (Pb-Free)	2500 Units / Tape & Reel	
MC34268DT	DPAK-3	75 Units / Rail	
MC34268DTG	DPAK-3 (Pb-Free)	75 Units / Rail	
MC34268DTRK	DPAK-3	2500 Units / Tape & Reel	
MC34268DTRKG	DPAK-3 (Pb-Free)	2500 Units / Tape & Reel	
MC34268STT3	SOT-223	4000 Units / Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **PACKAGE DIMENSIONS**

### SOIC-8 **D SUFFIX** CASE 751-07 **ISSUE AB**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

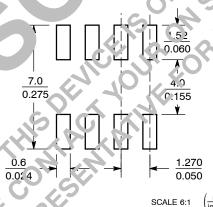
  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER CIDE.
- . MAXIMUM MOLD PHOTHUSION 0.15 (0.006) PER SIDE.
  . DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	YAI.
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0 50	0.157
c	1.35	1.75	0.000	0.069
D	0.33	0.5	0.013	0.020
G	1.27 PS		0.050 BSC	
Н	0.10	υ. <sup>2</sup> 5	0.004	0.010
7	0.10	^. <b>2</b> 5	0.0.17	0.010
K	1,4	1.27	U 770	0.050
M	. 0	8 2	υ°	8 °
Ļ	.25	ე., ე	J.010	0.020
	5.80	20	0.228	0.244

### SOLE RING FOOTPS. M.

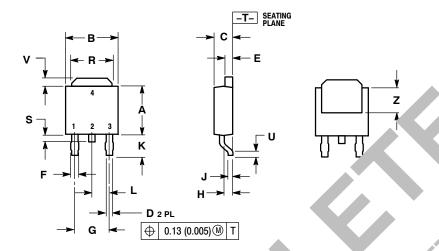


### SOIC-8

\*If or additional information on our Pb-Free strategy and soldering details please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **PACKAGE DIMENSIONS**

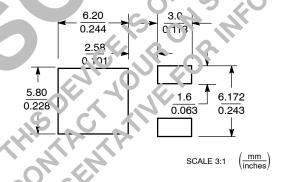
DPAK-3 **DT SUFFIX** CASE 369A-13 **ISSUE AB** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.250	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2 🕠	2.89
L	0.090 BSC		2. 19 bSC	
R	0.175	0.215	4. 5	5.46
S	0.020	0.0%	v.51	1.27
U	0.020		0.51	
٧	0.030	7 OF )	0.77	1.27
Z	0.103		3.51	

## RING FOOTPRINT

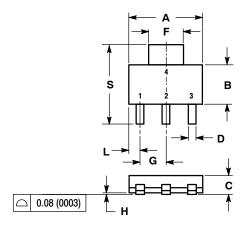


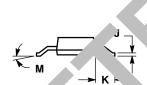
### DPAK-3

¬∵additiona information on our Pb–Free strategy and soldering Letails, Divise download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS

### SOT-223 ST SUFFIX CASE 318E-04 ISSUE K



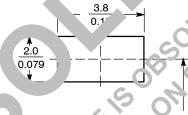


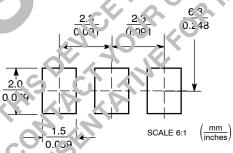
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   MARKA 1999
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.249	0.263	6.30	6.70
В	0.130	0.145	3.30	3.70
С	0.060	0.068	1.50	1.75
D	0.024	0.035	0.60	0.89
F	0.115	0.126	2.90	3.20
G	0.087	0.094	2.20	2.40
μ	0.0008	0.0040	0.020	0.100
	0.009	0.014	0.24	0.35
Α.	0.060	0.078	1.50	2.00
L	0.033	0.041	0.85	1.05
M	0 °	10 °	0 °	10
S	0.264	0.287	6,0	7.30







SOT-23

\*Fc, ad 'donal, 'donation on our Pb-Free strategy and soldering detrils, placine download the ON Semiconductor Soldering and Viounting Techniques Reference Manual, SOLDERRM/D.

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